

WHAT IS CLAIMED IS:

1. A semiconductor integrated circuit device, comprising a digital circuit part and an analog circuit part that are disposed on a surface of one semiconductor substrate,
 - 5 wherein a dummy layer part made of polysilicon that is the same as polysilicon composing a gate of a transistor is disposed between the digital circuit part and the analog circuit part.
- 10 2. The semiconductor integrated circuit device according to claim 1, wherein a dummy region further is provided between the digital circuit part and the analog circuit part, and a power-supply potential is applied to the dummy region.
- 15 3. The semiconductor integrated circuit device according to claim 1, wherein the digital circuit part is a circuit for driving a sensor array, and the analog circuit part is a circuit for analog processing an image detecting signal that is output from the sensor array.
- 20 4. The semiconductor integrated circuit device according to claim 3, wherein the sensor array is a CCD area sensor, a CCD linear sensor or a CMOS sensor.
- 25 5. A camera, comprising:
 - an imaging element; and
 - a semiconductor integrated circuit device comprising a digital circuit part for driving the imaging element and an analog circuit part for analog processing an image detecting signal output from the imaging element,
- 30 wherein the semiconductor integrated circuit device has a structure in which a dummy layer part made of polysilicon that is the same as polysilicon composing a gate of a transistor is disposed between the digital circuit part and the analog circuit part.